

Dear Sir/Madam,

I am interested in providing Microelectronics/MEMS fabrication, packaging, design and simulation services. I have experience in FEA and CFD. Please consider my qualification for the job referred. Please feel free to give my resume to your colleagues who may be interested.

As a MEMS Engineer and project lead at the University of Cincinnati's Center for Microelectronics Sensors and MEMS (CMSM), I was always quick to adapt to new and ever growing Microelectronics/MEMS field. As a team member, I learnt that the whole team has to look good for me to look good. This has taken my interpersonal skills to the next level. I am a self motivated person, requiring least supervision. Projects with NASA, NSF and EPRI which have rigid dead lines, have given me experience in planning and executing my work on a timely basis.

I am eager to relocate for the right opportunity. I am confident that my professional services would be beneficial to your organization. If you are interested in a results-oriented and dedicated professional, please call me at (513)751-7720. I am available for a telephone interview or an in-person meeting at your convenience. Thanks again for your time and assistance.

Sincerely yours,

Srinivas Parimi

References:

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